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[Continued on next page]

(54) **Title**: FULLY MOLDED FAN-OUT

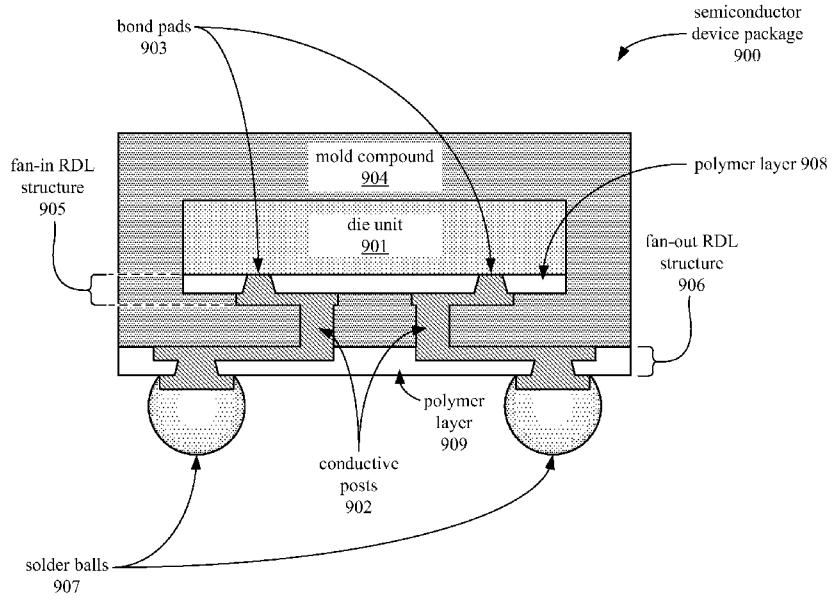


FIGURE 9

[Continued on next page]

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(57) Abstract: A method for manufacturing a device package may include constructing a spacer element coupled with a surface of a semiconductor die unit, where the spacer element is configured to create a gap between the semiconductor die unit and a surface of a carrier, and encapsulating the semiconductor die unit within a mold compound, where the encapsulating includes introducing the mold compound into the gap.